PRODUCT AND PROCESS CHANGE NOTIFICATION

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ISSUE DATE:	24-Jul-2015
NOTIFICATION:	16824
TITLE:	QFN PACKAGE (4X4, 5X5, 7X7) ASSEMBLY SITE EXPAND TO UNITED TEST AND ASSEMBLY CENTER LTD
EFFECTIVE DATE:	04-Nov-2015

DEVICE(S)

MPN
MC13201FC
MC13201FCR2
MC13202FC
MC13202FCR2
MC9RS08KB12CFK
MC9RS08KB4CFK
MC9RS08LA8CFT
MC9S08AC16CFDE
MC9S08AC16MFDE
MC9S08AC32CFDE
MC9S08AC48CFDE
MC9S08AC60CFDE
MC9S08AC60MFDE
MC9S08AC8CFDE
MC9S08AC8MFDE
MC9S08AW16CFDE
MC9S08AW16MFDE
MC9S08AW32CFDE
MC9S08AW32CFDER
MC9S08AW48CFDE
MC9S08AW60CFDE
MC9S08AW60MFDE
MC9S08GT16ACFCE
MC9S08GT16ACFCER
MC9S08GT16ACFDE
MC9S08GT16ACFDER

MC9S08GT16AMFCE
MC9S08GT16AMFDE
MC9S08GT32ACFDE
MC9S08GT32ACFDER
MC9S08GT60ACFDE
MC9S08GT60ACFDER
MC9S08GT8ACFCE
MC9S08GT8ACFDE
MC9S08GT8AMFCE
MC9S08GT8AMFDE
MC9S08JM16CGT
MC9S08JM32CGT
MC9S08JM60CGT
MC9S08JM8CGT
MC9S08LL16CGT
MC9S08LL16CGTR
MC9S08LL8CGT
MC9S08QE128CFT
MC9S08QE16CFM
MC9S08QE16CFT
MC9S08QE32CFM
MC9S08QE32CFMR
MC9S08QE32CFT
MC9S08QE64CFT
MC9S08QE96CFT
MC9S08QE96CFTR
MC9S08QG4CFKE
MC9S08QG8CFKE
MC9S08SH4CFK
MC9S08SH8CFK
MC9S08SH8MFK
MCF51CN128CGT
MCHC908JW16FC
MCHC908JW32FC

AFFECTED CHANGE CATEGORIES

- ASSEMBLY SITE

DESCRIPTION OF CHANGE

Freescale Semiconductor is announcing the assembly site expansion for the products listed in this notification from the current Freescale Tianjin, China (FSL-TJN-FM) assembly Facility to the Subcon UDG (United Test and Assembly Center Ltd), Dongguan, China assembly Facility.

REASON FOR CHANGE

Qualification of the Subcon UDG (United Test and Assembly Center Ltd), Dongguan, China assembly Facility to ensure manufacturing flexibility and customer supply assurance.

ANTICIPATED IMPACT OF PRODUCT CHANGE(FORM, FIT, FUNCTION, OR RELIABILITY)

There is no impact to device form, fit, function or reliability.

According to JEDEC Standard JESD46, lack of acknowledgement of this PCN within 30 days will be considered acceptance of change. To request further data or inquire about the notification, please enter a **Service Request.**

For sample inquiries - please go to www.freescale.com

QUAL DATA AVAILABILITY DATE: 22-Sep-2015

QUALIFICATION STATUS: IN PROCESS

QUALIFICATION PLAN:

Freescale Semiconductor Manufacturing standard specification for assembly transfers was followed for the Assembly Transfer.

RELIABILITY DATA SUMMARY:

Will provide upon request.

ELECTRICAL CHARACTERISTIC SUMMARY:

No change was made to the operating performance of the device. Electrical characterization of the device was not required.

CHANGED PART IDENTIFICATION:

The assembly site, among other information, is reflected in the QFN 5*5 and 7*7 package trace code.

The current assembly site marking for FSL-TJN-FM is A=CT.

The marking for proposed assembly UDG is A=CR.

Below sample parts from UDG are available for customer to order through the Service Request system. Other samples on PCN device list, need 4 weeks cycle time for delivery from customer ordering date.

Freescale Part Number	Sample Part Number from UDG	Package Description
MC9S08GT60ACFDE	PC9S08GT60ACFDE	QFN 48 EP 7SQ*1.0P0.5
MCF51CN128CGT	PCF51CN128CGT	QFN 48 EP 7SQ*1.0P0.5
MC9S08QE128CFT	PC9S08QE128CFT	QFN 48 EP 7SQ*1.0P0.5
MC13202FC	PC13202FC	QFN 32 EP 5SQ*1.0P0.5/6147

SAMPLE AVAILABILITY DATE: 06-Aug-2015

ATTACHMENT(S):

N/A